

## Product / Process Change Notice

**Parts Affected:**

CPD04 wafer process: 0.5 Amp, glass passivated, standard recovery rectifiers.

**Extent of Change:**

Overall wafer thickness has been increased from 8.5 mils to 10.5 mils.

**Reason for Change:**

To reduce wafer breakage during manufacturing processes.

**Effect of Change:**

This change does not affect the electrical characteristics of any device.

**Qualification:**

Standard evaluation and qualifications completed resulting in no performance differences compared to current product.

**Effective Date of Change:**

Existing inventory will be shipped until depleted.

**Sample Availability:**

Please contact Salesperson or Manufacturer's Representative.

**Part #'s Affected:**

CBRHD-01  
CBRHD-02  
CBRHD-04  
CBRHD-06  
CPD04-CBRHD-06-WN  
CPD04-CBRHD-06-WN  
CPD04-1N645-WR  
CPD04-1N647-CT  
CPD04-1N647-WN  
CPD04-1N649-CT  
CPD04-1N649-WN